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What are [Embedded - System On Chip \(SoC\)](#)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Quad ARM® Cortex®-A53 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 2800K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-FBGA, FC (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/intel/1sx280ln2f43e2lg



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1. Intel® Stratix® 10 GX/SX Device Overview

Intel's 14-nm Intel® Stratix® 10 GX FPGAs and SX SoCs deliver 2X the core performance and up to 70% lower power over previous generation high-performance FPGAs.

Featuring several groundbreaking innovations, including the all new HyperFlex™ core architecture, this device family enables you to meet the demand for ever-increasing bandwidth and processing performance in your most advanced applications, while meeting your power budget.

With an embedded hard processor system (HPS) based on a quad-core 64-bit ARM® Cortex®-A53, the Intel Stratix 10 SoC devices deliver power efficient, application-class processing and allow designers to extend hardware virtualization into the FPGA fabric. Intel Stratix 10 SoC devices demonstrate Intel's commitment to high-performance SoCs and extend Intel's leadership in programmable devices featuring an ARM-based processor system.

Important innovations in Intel Stratix 10 FPGAs and SoCs include:

- All new HyperFlex core architecture delivering 2X the core performance compared to previous generation high-performance FPGAs
- Industry leading Intel 14-nm Tri-Gate (FinFET) technology
- Heterogeneous 3D System-in-Package (SiP) technology
- Monolithic core fabric with up to 5.5 million logic elements (LEs)
- Up to 96 full duplex transceiver channels on heterogeneous 3D SiP transceiver tiles
- Transceiver data rates up to 28.3 Gbps chip-to-chip/module and backplane performance
- M20K (20 kbit) internal SRAM memory blocks
- Fractional synthesis and ultra-low jitter LC tank based transmit phase locked loops (PLLs)
- Hard PCI Express® Gen3 x16 intellectual property (IP) blocks
- Hard 10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC) in every transceiver channel
- Hard memory controllers and PHY supporting DDR4 rates up to 2666 Mbps per pin
- Hard fixed-point and IEEE 754 compliant hard floating-point variable precision digital signal processing (DSP) blocks with up to 10 TFLOPS compute performance with a power efficiency of 80 GFLOPS per Watt
- Quad-core 64-bit ARM Cortex-A53 embedded processor running up to 1.5 GHz in SoC family variants
- Programmable clock tree synthesis for flexible, low power, low skew clock trees

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- Dedicated secure device manager (SDM) for:
 - Enhanced device configuration and security
 - AES-256, SHA-256/384 and ECDSA-256/384 encrypt/decrypt accelerators and authentication
 - Multi-factor authentication
 - Physically Unclonable Function (PUF) service and software programmable device configuration capability
- Comprehensive set of advanced power saving features delivering up to 70% lower power compared to previous generation high-performance FPGAs
- Non-destructive register state readback and writeback, to support ASIC prototyping and other applications

With these capabilities, Intel Stratix 10 FPGAs and SoCs are ideally suited for the most demanding applications in diverse markets such as:

- **Compute and Storage**—for custom servers, cloud computing and data center acceleration
- **Networking**—for Terabit, 400G and multi-100G bridging, aggregation, packet processing and traffic management
- **Optical Transport Networks**—for OTU4, 2xOTU4, 4xOTU4
- **Broadcast**—for high-end studio distribution, headend encoding/decoding, edge quadrature amplitude modulation (QAM)
- **Military**—for radar, electronic warfare, and secure communications
- **Medical**—for diagnostic scanners and diagnostic imaging
- **Test and Measurement**—for protocol and application testers
- **Wireless**—for next-generation 5G networks
- **ASIC Prototyping**—for designs that require the largest monolithic FPGA fabric with the highest I/O count

1.1. Intel Stratix 10 Family Variants

Intel Stratix 10 devices are available in FPGA (GX) and SoC (SX) variants.

- **Intel Stratix 10 GX** devices deliver up to 1 GHz core fabric performance and contain up to 5.5 million LEs in a monolithic fabric. They also feature up to 96 general purpose transceivers on separate transceiver tiles, and 2666 Mbps DDR4 external memory interface performance. The transceivers are capable of up to 28.3 Gbps short reach and across the backplane. These devices are optimized for FPGA applications that require the highest transceiver bandwidth and core fabric performance, with the power efficiency of Intel's industry-leading 14-nm Tri-Gate process technology.
- **Intel Stratix 10 SX** devices have a feature set that is identical to Intel Stratix 10 GX devices, with the addition of an embedded quad-core 64-bit ARM Cortex A53 hard processor system.



Common to all Intel Stratix 10 family variants is a high-performance fabric based on the new HyperFlex core architecture that includes additional Hyper-Registers throughout the interconnect routing and at the inputs of all functional blocks. The core fabric also contains an enhanced logic array utilizing Intel's adaptive logic module (ALM) and a rich set of high performance building blocks including:

- M20K (20 kbit) embedded memory blocks
- Variable precision DSP blocks with hard IEEE 754 compliant floating-point units
- Fractional synthesis and integer PLLs
- Hard memory controllers and PHY for external memory interfaces
- General purpose IO cells

To clock these building blocks, Intel Stratix 10 devices use programmable clock tree synthesis, which uses dedicated clock tree routing to synthesize only those branches of the clock trees required for the application. All devices support in-system, fine-grained partial reconfiguration of the logic array, allowing logic to be added and subtracted from the system while it is operating.

All family variants also contain high speed serial transceivers, containing both the physical medium attachment (PMA) and the physical coding sublayer (PCS), which can be used to implement a variety of industry standard and proprietary protocols. In addition to the hard PCS, Intel Stratix 10 devices contain multiple instantiations of PCI Express hard IP that supports Gen1/Gen2/Gen3 rates in x1/x2/x4/x8/x16 lane configurations, and hard 10GBASE-KR/40GBASE-KR4 FEC for every transceiver. The hard PCS, FEC, and PCI Express IP free up valuable core logic resources, save power, and increase your productivity.



Feature	Stratix V FPGAs	Intel Stratix 10 FPGAs and SoCs
Logic density	952 KLE (monolithic)	5,500 KLE (monolithic)
Embedded memory (M20K)	52 Mbits	229 Mbits
18x19 multipliers	3,926 <i>Note:</i> Multiplier is 18x18 in Stratix V devices.	11,520 <i>Note:</i> Multiplier is 18x19 in Intel Stratix 10 devices.
Floating point DSP capability	Up to 1 TFLOP, requires soft floating point adder and multiplier	Up to 10 TFLOPS, hard IEEE 754 compliant single precision floating point adder and multiplier
Maximum transceivers	66	96
Maximum transceiver data rate (chip-to-chip)	28.05 Gbps	28.3 Gbps L-Tile 28.3 Gbps H-Tile
Maximum transceiver data rate (backplane)	12.5 Gbps	12.5 Gbps L-Tile 28.3 Gbps H-Tile
Hard memory controller	None	DDR4 @ 1333 MHz/2666 Mbps DDR3 @ 1067 MHz/2133 Mbps
Hard protocol IP	PCIe Gen3 x8 (up to 4 instances)	PCIe Gen3 x16 (up to 4 instances) SR-IOV (4 physical functions / 2k virtual functions) on H-Tile devices 10GBASE-KR/40GBASE-KR4 FEC
Core clocking and PLLs	Global, quadrant and regional clocks supported by fractional-synthesis fPLLs	Programmable clock tree synthesis supported by fractional synthesis fPLLs and integer IO PLLs
Register state readback and writeback	Not available	Non-destructive register state readback and writeback for ASIC prototyping and other applications

These innovations result in the following improvements:

- **Improved Core Logic Performance:** The HyperFlex core architecture combined with Intel's 14-nm Tri-Gate technology allows Intel Stratix 10 devices to achieve 2X the core performance compared to the previous generation
- **Lower Power:** Intel Stratix 10 devices use up to 70% lower power compared to the previous generation, enabled by 14-nm Intel Tri-Gate technology, the HyperFlex core architecture, and optional power saving features built into the architecture
- **Higher Density:** Intel Stratix 10 devices offer over five times the level of integration, with up to 5,500K logic elements (LEs) in a monolithic fabric, over 229 Mbits of embedded memory blocks (M20K), and 11,520 18x19 multipliers
- **Embedded Processing:** Intel Stratix 10 SoCs feature a Quad-Core 64-bit ARM Cortex-A53 processor optimized for power efficiency and software compatible with previous generation Arria and Cyclone SoC devices
- **Improved Transceiver Performance:** With up to 96 transceiver channels implemented in heterogeneous 3D SiP transceiver tiles, Intel Stratix 10 GX and SX devices support data rates up to 28.3 Gbps chip-to-chip and 28.3 Gbps across the backplane with signal conditioning circuits capable of equalizing over 30 dB of system loss
- **Improved DSP Performance:** The variable precision DSP block in Intel Stratix 10 devices features hard fixed and floating point capability, with up to 10 TeraFLOPS IEEE754 single-precision floating point performance



Feature	Description
Power management	<ul style="list-style-type: none"> SmartVID controlled core voltage, standard power devices 0.85-V fixed core voltage, low static power devices available Intel Quartus® Prime Pro Edition integrated power analysis
High performance monolithic core fabric	<ul style="list-style-type: none"> HyperFlex core architecture with Hyper-Registers throughout the interconnect routing and at the inputs of all functional blocks Monolithic fabric minimizes compile times and increases logic utilization Enhanced adaptive logic module (ALM) Improved multi-track routing architecture reduces congestion and improves compile times Hierarchical core clocking architecture with programmable clock tree synthesis Fine-grained partial reconfiguration
Internal memory blocks	<ul style="list-style-type: none"> M20K—20-Kbit with hard ECC support MLAB—640-bit distributed LUTRAM
Variable precision DSP blocks	<ul style="list-style-type: none"> IEEE 754-compliant hard single-precision floating point capability Supports signal processing with precision ranging from 18x19 up to 54x54 Native 27x27 and 18x19 multiply modes 64-bit accumulator and cascade for systolic FIRs Internal coefficient memory banks Pre-adder/subtractor improves efficiency Additional pipeline register increases performance and reduces power
Phase locked loops (PLL)	<ul style="list-style-type: none"> Fractional synthesis PLLs (fPLL) support both fractional and integer modes Fractional mode with third-order delta-sigma modulation Precision frequency synthesis Integer PLLs adjacent to general purpose I/Os, support external memory, and LVDS interfaces, clock delay compensation, zero delay buffering
Core clock networks	<ul style="list-style-type: none"> 1 GHz fabric clocking 667 MHz external memory interface clocking, supports 2666 Mbps DDR4 interface 800 MHz LVDS interface clocking, supports 1600 Mbps LVDS interface Programmable clock tree synthesis, backwards compatible with global, regional and peripheral clock networks Clocks only synthesized where needed, to minimize dynamic power
continued...	



Table 4. Intel Stratix 10 GX/SX FPGA and SoC Family Plan—FPGA Core (part 1)

Intel Stratix 10 GX/SX Device Name	Logic Elements (KLE)	M20K Blocks	M20K Mbits	MLAB Counts	MLAB Mbits	18x19 Multipliers ⁽¹⁾
GX 400/ SX 400	378	1,537	30	3,204	2	1,296
GX 650/ SX 650	612	2,489	49	5,184	3	2,304
GX 850/ SX 850	841	3,477	68	7,124	4	4,032
GX 1100/ SX 1100	1,092	4,401	86	9,540	6	5,040
GX 1650/ SX 1650	1,624	5,851	114	13,764	8	6,290
GX 2100/ SX 2100	2,005	6,501	127	17,316	11	7,488
GX 2500/ SX 2500	2,422	9,963	195	20,529	13	10,022
GX 2800/ SX 2800	2,753	11,721	229	23,796	15	11,520
GX 4500/ SX 4500	4,463	7,033	137	37,821	23	3,960
GX 5500/ SX 5500	5,510	7,033	137	47,700	29	3,960

Table 5. Intel Stratix 10 GX/SX FPGA and SoC Family Plan—Interconnects, PLLs and Hard IP (part 2)

Intel Stratix 10 GX/SX Device Name	Interconnects		PLLs		Hard IP
	Maximum GPIOs	Maximum XCVR	fPLLs	I/O PLLs	PCIe Hard IP Blocks
GX 400/ SX 400	392	24	8	8	1
GX 650/ SX 650	400	48	16	8	2
GX 850/ SX 850	736	48	16	15	2
GX 1100/ SX 1100	736	48	16	15	2
GX 1650/ SX 1650	704	96	32	14	4
GX 2100/ SX 2100	704	96	32	14	4
GX 2500/ SX 2500	1160	96	32	24	4
continued...					



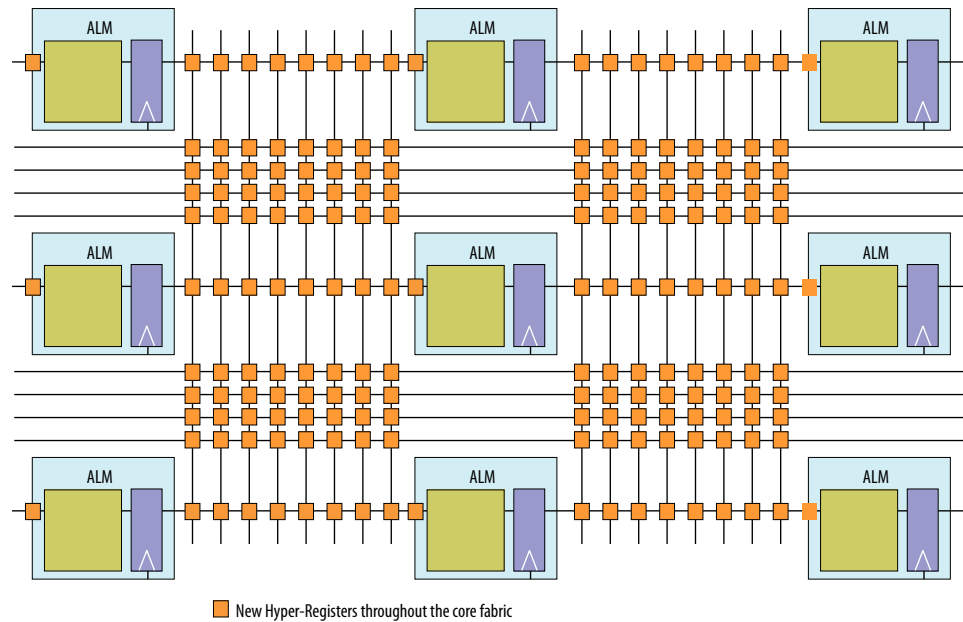
Intel Stratix 10 GX/SX Device Name	F1152 HF35 (35x35 mm ²)	F1760 NF43 (42.5x42.5 mm ²)	F1760 NF43 (42.5x42.5 mm ²)
SX 2800			
GX 4500/ SX 4500			
GX 5500/ SX 5500			

Table 7. Intel Stratix 10 GX/SX FPGA and SoC Family Package Plan, part 2

Cell legend: General Purpose I/Os, High-Voltage I/Os, LVDS Pairs, Transceivers ⁽²⁾ ⁽³⁾ ⁽⁴⁾ ⁽⁵⁾ ⁽⁶⁾ ⁽⁷⁾

Intel Stratix 10 GX/SX Device Name	F2112 NF48 (47.5x47.5 mm ²)	F2397 UF50 (50x50 mm ²)	F2912 HF55 (55x55 mm ²)
GX 400/ SX 400			
GX 650/ SX 650			
GX 850/ SX 850	736, 16, 360, 48		
GX 1100/ SX 1100	736, 16, 360, 48		
GX 1650/ SX 1650		704, 32, 336, 96	
GX 2100/ SX 2100		704, 32, 336, 96	
GX 2500/ SX 2500		704, 32, 336, 96	1160, 8, 576, 24
GX 2800/ SX 2800		704, 32, 336, 96	1160, 8, 576, 24
GX 4500/ SX 4500			1640, 8, 816, 24
GX 5500/ SX 5500			1640, 8, 816, 24

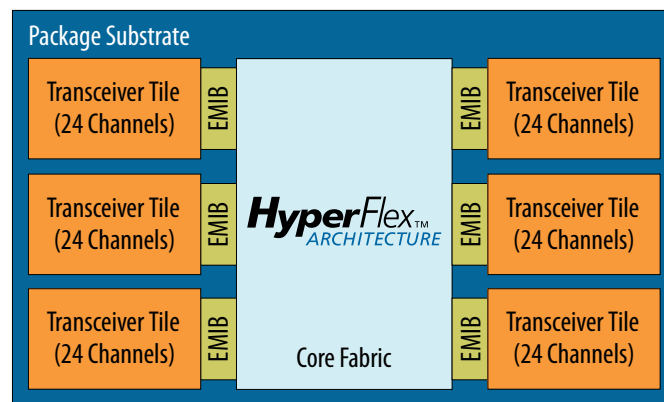
Figure 4. HyperFlex Core Architecture



1.7. Heterogeneous 3D SiP Transceiver Tiles

Intel Stratix 10 FPGAs and SoCs feature power efficient, high bandwidth, low latency transceivers. The transceivers are implemented on heterogeneous 3D System-in-Package (SiP) transceiver tiles, each containing 24 full-duplex transceiver channels. In addition to providing a high-performance transceiver solution to meet current connectivity needs, this allows for future flexibility and scalability as data rates, modulation schemes, and protocol IPs evolve.

Figure 5. Monolithic Core Fabric and Heterogeneous 3D SiP Transceiver Tiles





Within each transceiver tile, the transceivers are arranged in four banks of six PMA-PCS groups. A wide variety of bonded and non-bonded data rate configurations are possible within each bank, and within each tile, using a highly configurable clock distribution network.

1.8.1. PMA Features

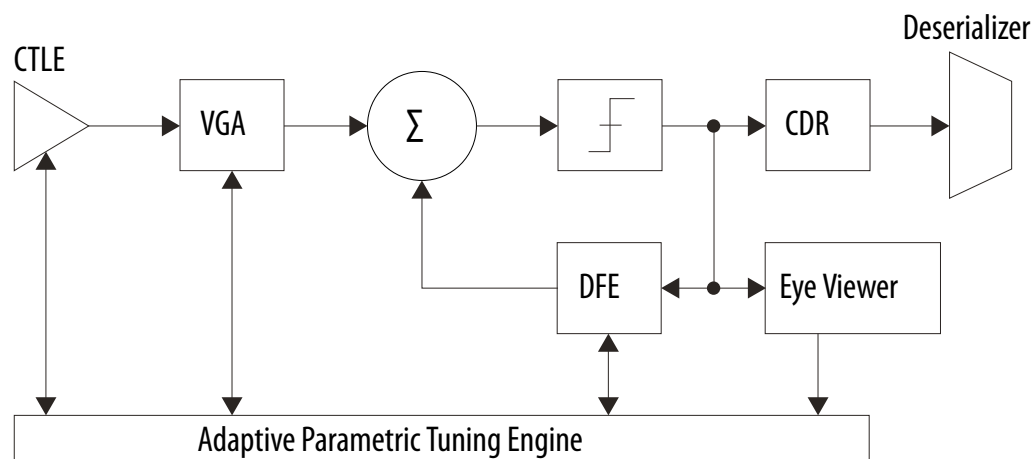
PMA channels are comprised of transmitter (TX), receiver (RX), and high speed clocking resources.

Intel Stratix 10 device features provide exceptional signal integrity at data rates up to 28.3 Gbps. Clocking options include ultra-low jitter LC tank-based (ATX) PLLs with optional fractional synthesis capability, channel PLLs operating as clock multiplier units (CMUs), and fractional synthesis PLLs (fPLLs).

- **ATX PLL**—can be configured in integer mode, or optionally, in a new fractional synthesis mode. Each ATX PLL spans the full frequency range of the supported data rate range providing a stable, flexible clock source with the lowest jitter.
- **CMU PLL**—when not being used as a transceiver, select PMA channels can be configured as channel PLLs operating as CMUs to provide an additional master clock source within the transceiver bank.
- **fPLL**—In addition, dedicated fPLLs are available with precision frequency synthesis capabilities. fPLLs can be used to synthesize multiple clock frequencies from a single reference clock source and replace multiple reference oscillators for multi-protocol and multi-rate applications.

On the receiver side, each PMA has an independent channel PLL that allows analog tracking for clock-data recovery. Each PMA also has advanced equalization circuits that compensate for transmission losses across a wide frequency spectrum.

- **Variable Gain Amplifier (VGA)**—to optimize the receiver's dynamic range
- **Continuous Time Linear Equalizer (CTLE)**—to compensate for channel losses with lowest power dissipation
- **Decision Feedback Equalizer (DFE)**—to provide additional equalization capability on backplanes even in the presence of crosstalk and reflections
- **On-Die Instrumentation (ODI)**—to provide on-chip eye monitoring capabilities (Eye Viewer). This capability helps to optimize link equalization parameters during board bring-up and supports in-system link diagnostics and equalization margin testing

**Figure 7. Intel Stratix 10 Receiver Block Features**

All link equalization parameters feature automatic adaptation using the new Advanced Digital Adaptive Parametric Tuning (ADAPT) circuit. This circuit is used to dynamically set DFE tap weights, adjust CTLE parameters, and optimize VGA gain and threshold voltage. Finally, optimal and consistent signal integrity is ensured by using the new hardened Precision Signal Integrity Calibration Engine (PreSICE) to automatically calibrate all transceiver circuit blocks on power-up. This gives the most link margin and ensures robust, reliable, and error-free operation.

Table 8. Transceiver PMA Features

Feature	Capability
Chip-to-Chip Data Rates	1 Gbps ⁽⁸⁾ to 28.3 Gbps (Intel Stratix 10 GX/SX devices)
Backplane Support	Drive backplanes at data rates up to 28.3 Gbps, including 10GBASE-KR compliance
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, QSFPDD, CFP/CFP2/CFP4
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA
Transmit Pre-Emphasis	5-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss
Decision Feedback Equalizer (DFE)	15 fixed tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments
Advanced Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters—including CTLE, DFE, and VGA blocks—that provide optimal link margin without intervention from user logic
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance
ATX Transmit PLLs	Low jitter ATX (inductor-capacitor) transmit PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols, with optional fractional frequency synthesis capability
Fractional PLLs	On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost

continued...

⁽⁸⁾ Stratix 10 transceivers can support data rates below 1 Gbps with over sampling.



The core clock network in Intel Stratix 10 devices supports the new HyperFlex core architecture at clock rates up to 1 GHz. It also supports the hard memory controllers up to 2666 Mbps with a quarter rate transfer to the core. The core clock network is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

1.15. Fractional Synthesis PLLs and I/O PLLs

Intel Stratix 10 devices have up to 32 fractional synthesis PLLs (fPLL) available for use with transceivers or in the core fabric.

The fPLLs are located in the 3D SiP transceiver H-tiles, eight per tile, adjacent to the transceiver channels. The fPLLs can be used to reduce both the number of oscillators required on the board and the number of clock pins required, by synthesizing multiple clock frequencies from a single reference clock source. In addition to synthesizing reference clock frequencies for the transceiver transmit PLLs, the fPLLs can also be used directly for transmit clocking. Each fPLL can be independently configured for conventional integer mode, or enhanced fractional synthesis mode with third-order delta-sigma modulation.

In addition to the fPLLs, Intel Stratix 10 devices contain up to 34 integer I/O PLLs (IOPLLs) available for general purpose use in the core fabric and for simplifying the design of external memory interfaces and high-speed LVDS interfaces. The IOPLLs are located in each bank of 48 general purpose I/O, 1 per I/O bank, adjacent to the hard memory controllers and LVDS SerDes in each I/O bank. This makes it easier to close timing because the IOPLLs are tightly coupled with the I/Os that need to use them. The IOPLLs can be used for general purpose applications in the core such as clock network delay compensation and zero-delay clock buffering.

1.16. Internal Embedded Memory

Intel Stratix 10 devices contain two types of embedded memory blocks: M20K (20-Kbit) and MLAB (640-bit).

The M20K and MLAB blocks are familiar block sizes carried over from previous Intel device families. The MLAB blocks are ideal for wide and shallow memories, while the M20K blocks are intended to support larger memory configurations and include hard ECC. Both M20K and MLAB embedded memory blocks can be configured as a single-port or dual-port RAM, FIFO, ROM, or shift register. These memory blocks are highly flexible and support a number of memory configurations as shown in [Table 11](#) on page 25.

Table 11. Internal Embedded Memory Block Configurations

MLAB (640 bits)	M20K (20 Kbits)
64 x 10 (supported through emulation) 32 x 20	2K x 10 (or x8) 1K x 20 (or x16) 512 x 40 (or x32)

1.17. Variable Precision DSP Block

The Intel Stratix 10 DSP blocks are based upon the Variable Precision DSP Architecture used in Intel's previous generation devices. They feature hard fixed point and IEEE-754 compliant floating point capability.

The DSP blocks can be configured to support signal processing with precision ranging from 18x19 up to 54x54. A pipeline register has been added to increase the maximum operating frequency of the DSP block and reduce power consumption.

Figure 10. DSP Block: Standard Precision Fixed Point Mode

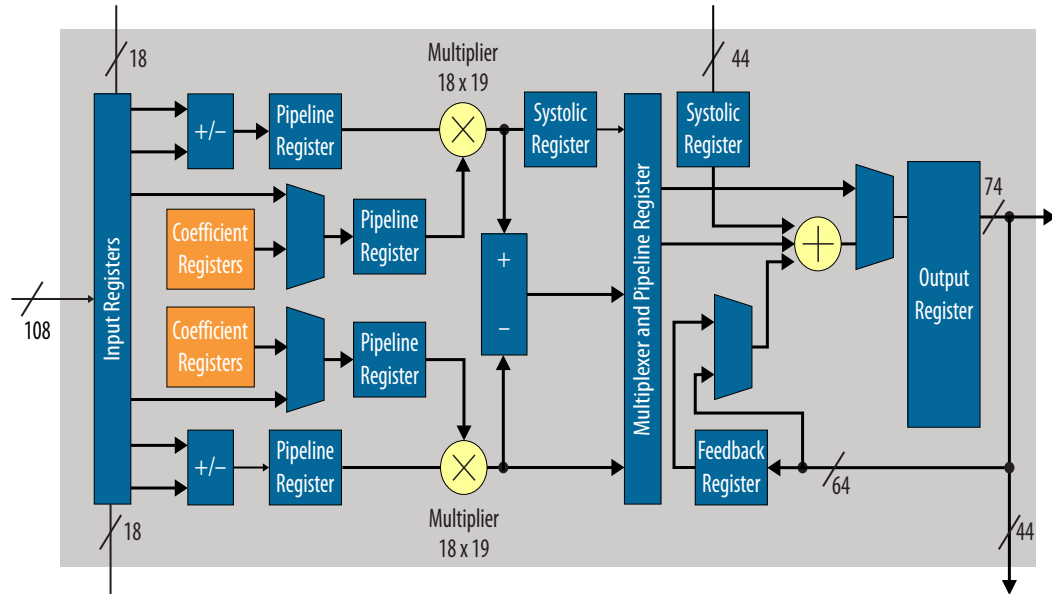


Figure 11. DSP Block: High Precision Fixed Point Mode

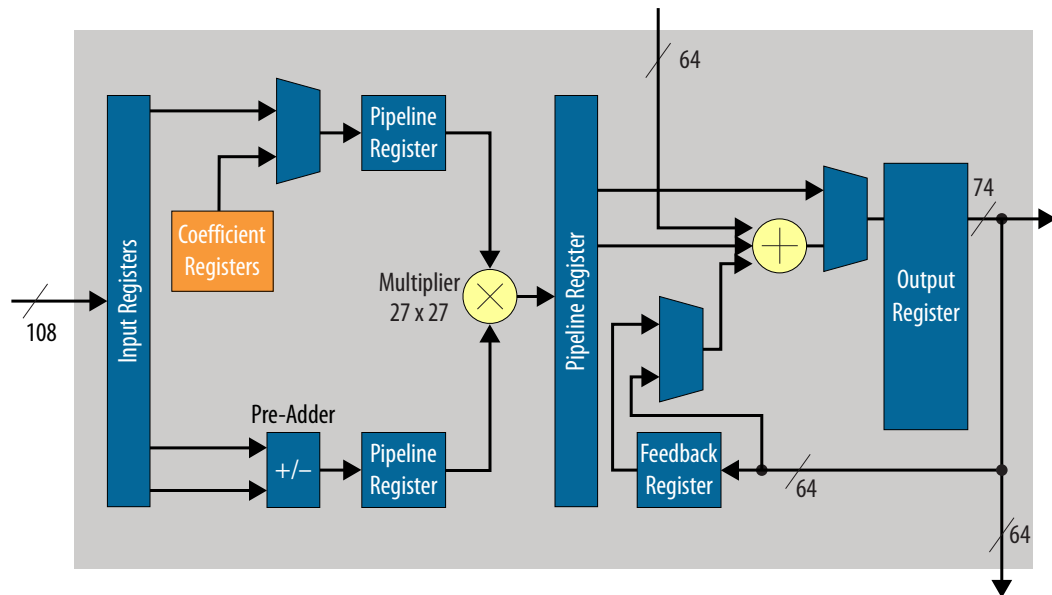
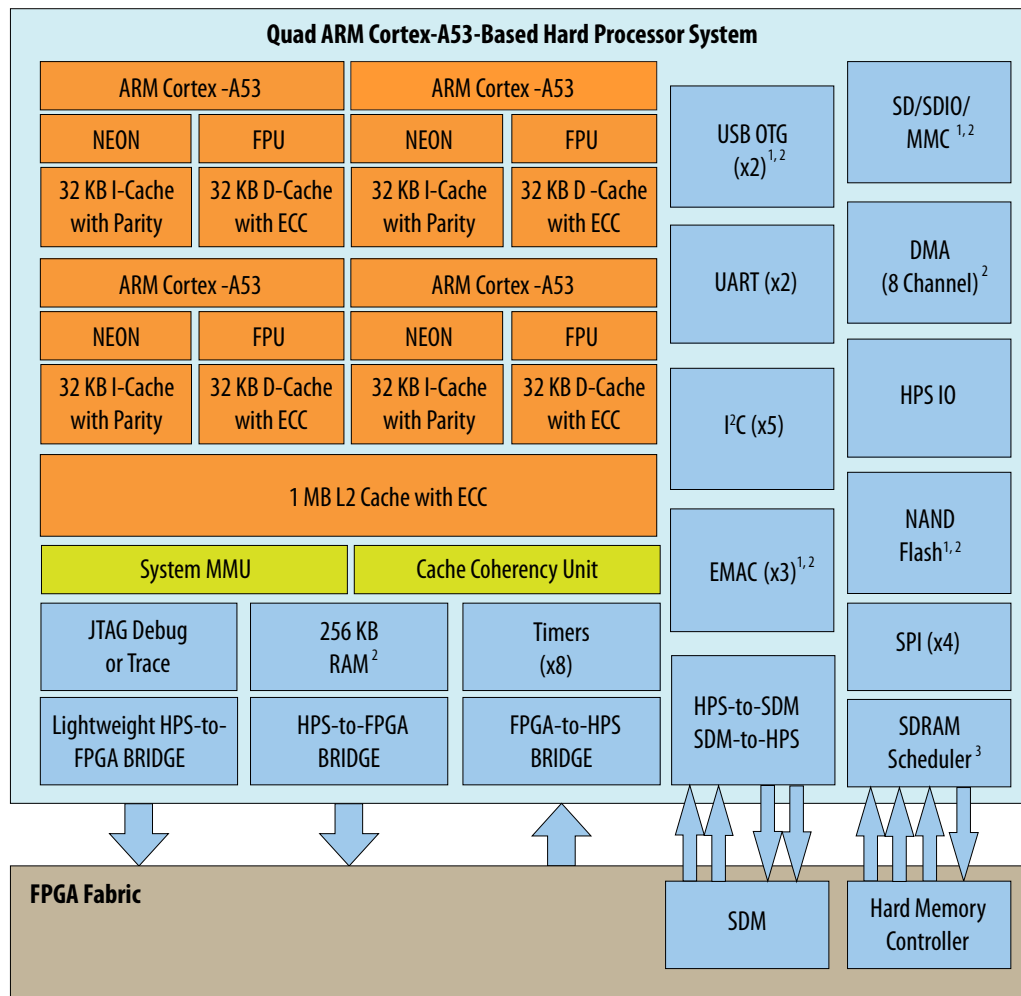




Figure 13. HPS Block Diagram



Notes:

1. Integrated direct memory access (DMA)
2. Integrated error correction code (ECC)
3. Multiport front-end interface to hard memory controller

1.18.1. Key Features of the Intel Stratix 10 HPS

Table 14. Key Features of the Intel Stratix 10 GX/SX HPS

Feature	Description
Quad-core ARM Cortex-A53 MPCore processor unit	<ul style="list-style-type: none"> • 2.3 MIPS/MHz instruction efficiency • CPU frequency up to 1.5 GHz • At 1.5 GHz total performance of 13,800 MIPS • ARMv8-A architecture • Runs 64-bit and 32-bit ARM instructions • 16-bit and 32-bit Thumb instructions for 30% reduction in memory footprint • Jazelle® RCT execution architecture with 8-bit Java bytecodes

continued...



Feature	Description
	<ul style="list-style-type: none"> Superscalar, variable length, out-of-order pipeline with dynamic branch prediction Improved ARM NEON™ media processing engine Single- and double-precision floating-point unit CoreSight™ debug and trace technology
System Memory Management Unit	<ul style="list-style-type: none"> Enables a unified memory model and extends hardware virtualization into peripherals implemented in the FPGA fabric
Cache Coherency unit	<ul style="list-style-type: none"> Changes in shared data stored in cache are propagated throughout the system providing bi-directional coherency for co-processing elements.
Cache	<ul style="list-style-type: none"> L1 Cache <ul style="list-style-type: none"> 32 KB of instruction cache w/ parity check 32 KB of L1 data cache w /ECC Parity checking L2 Cache <ul style="list-style-type: none"> 1MB shared 8-way set associative SEU Protection with parity on TAG ram and ECC on data RAM Cache lockdown support
On-Chip Memory	<ul style="list-style-type: none"> 256 KB of scratch on-chip RAM
External SDRAM and Flash Memory Interfaces for HPS	<ul style="list-style-type: none"> Hard memory controller with support for DDR4, DDR3, LPDDR3 <ul style="list-style-type: none"> 40-bit (32-bit + 8-bit ECC) with select packages supporting 72-bit (64-bit + 8-bit ECC) Support for up to 2666 Mbps DDR4 and 2166 Mbps DDR3 frequencies Error correction code (ECC) support including calculation, error correction, write-back correction, and error counters Software Configurable Priority Scheduling on individual SDRAM bursts Fully programmable timing parameter support for all JEDEC-specified timing parameters Multiport front-end (MPFE) scheduler interface to the hard memory controller, which supports the AXI® Quality of Service (QoS) for interface to the FPGA fabric NAND flash controller <ul style="list-style-type: none"> ONFI 1.0 Integrated descriptor based with DMA Programmable hardware ECC support Support for 8- and 16-bit Flash devices Secure Digital SD/SDIO/MMC controller <ul style="list-style-type: none"> eMMC 4.5 Integrated descriptor based DMA CE-ATA digital commands supported 50 MHz operating frequency Direct memory access (DMA) controller <ul style="list-style-type: none"> 8-channel Supports up to 32 peripheral handshake interface

continued...



Feature	Description
Communication Interface Controllers	<ul style="list-style-type: none"> Three 10/100/1000 Ethernet media access controls (MAC) with integrated DMA <ul style="list-style-type: none"> Supports RGMII and RMII external PHY Interfaces Option to support other PHY interfaces through FPGA logic <ul style="list-style-type: none"> GMII MII RMII (requires MII to RMII adapter) RGMII (requires GMII to RGMII adapter) SGMII (requires GMII to SGMII adapter) Supports IEEE 1588-2002 and IEEE 1588-2008 standards for precision networked clock synchronization Supports IEEE 802.1Q VLAN tag detection for reception frames Supports Ethernet AVB standard Two USB On-the-Go (OTG) controllers with DMA <ul style="list-style-type: none"> Dual-Role Device (device and host functions) <ul style="list-style-type: none"> High-speed (480 Mbps) Full-speed (12 Mbps) Low-speed (1.5 Mbps) Supports USB 1.1 (full-speed and low-speed) Integrated descriptor-based scatter-gather DMA Support for external ULPI PHY Up to 16 bidirectional endpoints, including control endpoint Up to 16 host channels Supports generic root hub Configurable to OTG 1.3 and OTG 2.0 modes Five I²C controllers (three can be used by EMAC for MIO to external PHY) <ul style="list-style-type: none"> Support both 100Kbps and 400Kbps modes Support both 7-bit and 10-bit addressing modes Support Master and Slave operating mode Two UART 16550 compatible <ul style="list-style-type: none"> Programmable baud rate up to 115.2Kbaud Four serial peripheral interfaces (SPI) (2 Master, 2 Slaves) <ul style="list-style-type: none"> Full and Half duplex
Timers and I/O	<ul style="list-style-type: none"> Timers <ul style="list-style-type: none"> 4 general-purpose timers 4 watchdog timers 48 HPS direct I/O allow HPS peripherals to connect directly to I/O Up to three IO48 banks may be assigned to HPS for HPS DDR access
Interconnect to Logic Core	<ul style="list-style-type: none"> FPGA-to-HPS Bridge <ul style="list-style-type: none"> Allows IP bus masters in the FPGA fabric to access to HPS bus slaves Configurable 32-, 64-, or 128-bit AMBA AXI interface HPS-to-FPGA Bridge <ul style="list-style-type: none"> Allows HPS bus masters to access bus slaves in FPGA fabric Configurable 32-, 64-, or 128-bit AMBA AXI interface allows high-bandwidth HPS master transactions to FPGA fabric HPS-to-SDM and SDM-to-HPS Bridges <ul style="list-style-type: none"> Allows the HPS to reach the SDM block and the SDM to bootstrap the HPS Light Weight HPS-to-FPGA Bridge <ul style="list-style-type: none"> Light weight 32-bit AXI interface suitable for low-latency register accesses from HPS to soft peripherals in FPGA fabric FPGA-to-HPS SDRAM Bridge <ul style="list-style-type: none"> Up to three AMBA AXI interfaces supporting 32, 64, or 128-bit data paths



1.19. Power Management

Intel Stratix 10 devices leverage the advanced Intel 14-nm Tri-Gate process technology, the all new HyperFlex core architecture to enable Hyper-Folding, power gating, and several optional power reduction techniques to reduce total power consumption by as much as 70% compared to previous generation high-performance Stratix V devices.

Intel Stratix 10 standard power devices (-V) are SmartVID devices. The core voltage supplies (VCC and VCCP) for each SmartVID device must be driven by a PMBus voltage regulator dedicated to that Intel Stratix 10 device. Use of a PMBus voltage regulator for each SmartVID (-V) device is mandatory; it is not an option. A code is programmed into each SmartVID device during manufacturing that allows the PMBus voltage regulator to operate at the optimum core voltage to meet the device performance specifications.

With the new HyperFlex core architecture, designs can run 2X faster than previous generation FPGAs. With 2X performance and same required throughput, architects can cut the data path width in half to save power. This optimization is called Hyper-Folding. Additionally, power gating reduces static power of unused resources in the FPGA by powering them down. The Intel Quartus Prime software automatically powers down specific unused resource blocks such as DSP and M20K blocks, at configuration time.

The optional power reduction techniques in Intel Stratix 10 devices include:

- **Available Low Static Power Devices**—Intel Stratix 10 devices are available with a fixed core voltage that provides lower static power than the SmartVID standard power devices, while maintaining device performance

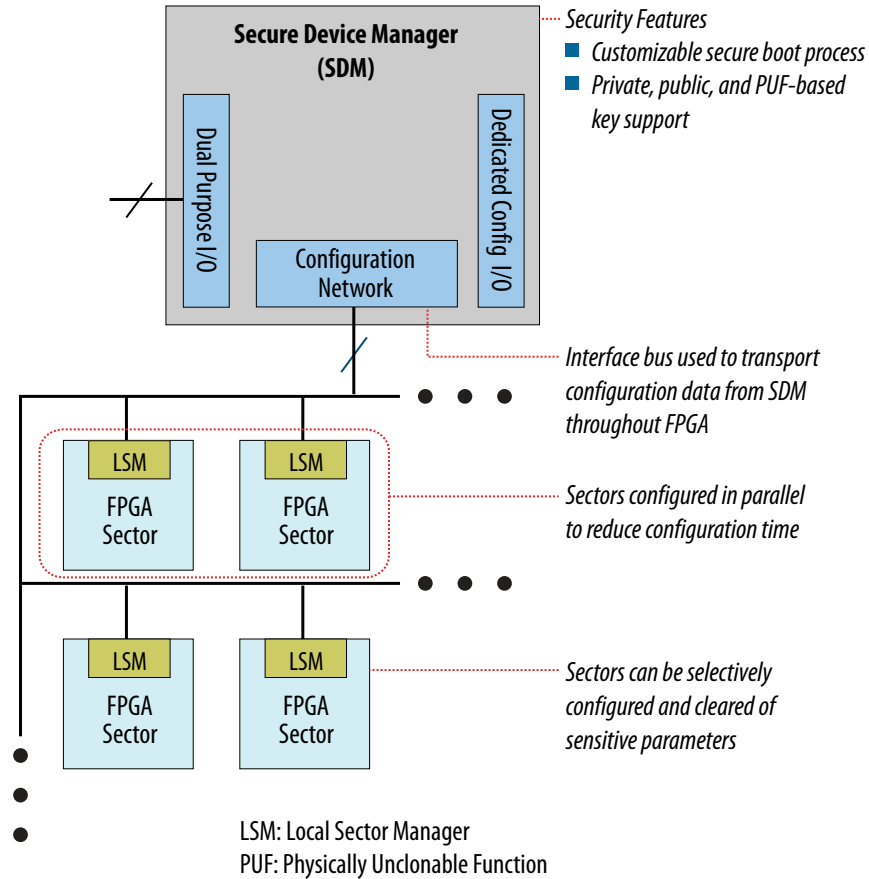
Furthermore, Intel Stratix 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 50% less power than the equivalent soft logic implementations.

1.20. Device Configuration and Secure Device Manager (SDM)

All Intel Stratix 10 devices contain a Secure Device Manager (SDM), which is a dedicated triple-redundant processor that serves as the point of entry into the device for all JTAG and configuration commands. The SDM also bootstraps the HPS in SoC devices ensuring that the HPS can boot using the same security features that the FPGA devices have.



Figure 14. SDM Block Diagram



During configuration, Intel Stratix 10 devices are divided into logical sectors, each of which is managed by a local sector manager (LSM). The SDM passes configuration data to each of the LSMs across the on-chip configuration network. This allows the sectors to be configured independently, one at a time, or in parallel. This approach achieves simplified sector configuration and reconfiguration, as well as reduced overall configuration time due to the inherent parallelism. The same sector-based approach is used to respond to single-event upsets and security attacks.

While the sectors provide a logical separation for device configuration and reconfiguration, they overlay the normal rows and columns of FPGA logic and routing. This means there is no impact to the Intel Quartus Prime software place and route, and no impact to the timing of logic signals that cross the sector boundaries.



The SDM enables robust, secure, fully-authenticated device configuration. It also allows for customization of the configuration scheme, which can enhance device security. For configuration and reconfiguration, this approach offers a variety of advantages:

- Dedicated secure configuration manager
- Reduced device configuration time, because sectors are configured in parallel
- Updateable configuration process
- Reconfiguration of one or more sectors independent of all other sectors
- Zeroization of individual sectors or the complete device

The SDM also provides additional capabilities such as register state readback and writeback to support ASIC prototyping and other applications.

1.21. Device Security

Building on top of the robust security features present in the previous generation devices, Intel Stratix 10 FPGAs and SoCs include a number of new and innovative security enhancements. These features are also managed by the SDM, tightly coupling device configuration and reconfiguration with encryption, authentication, key storage and anti-tamper services.

Security services provided by the SDM include:

- Bitstream encryption
- Multi-factor authentication
- Hard encryption and authentication acceleration; AES-256, SHA-256/384, ECDSA-256/384
- Volatile and non-volatile encryption key storage and management
- Boot code authentication for the HPS
- Physically Unclonable Function (PUF) service
- Updateable configuration process
- Secure device maintenance and upgrade functions
- Side channel attack protection
- Scripted response to sensor inputs and security attacks, including selective sector zeroization
- Readback, JTAG and test mode disable
- Enhanced response to single-event upsets (SEU)

The SDM and associated security services provide a robust, multi-layered security solution for your Intel Stratix 10 design.

1.22. Configuration via Protocol Using PCI Express

Configuration via protocol using PCI Express allows the FPGA to be configured across the PCI Express bus, simplifying the board layout and increasing system integration. Making use of the embedded PCI Express hard IP operating in autonomous mode before the FPGA is configured, this technique allows the PCI Express bus to be



The physical layout of the CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the user memories also include integrated ECC circuitry and are layout optimized for error detection and correction.

The SEU error detection and correction hardware is supported by both soft IP and the Intel Quartus Prime software to provide a complete SEU mitigation solution. The components of the complete solution include:

- Hard error detection and correction for CRAM and user M20K memory blocks
- Optimized physical layout of memory cells to minimize probability of SEU
- Sensitivity processing soft IP that reports if CRAM upset affects a used or unused bit
- Fault injection soft IP with the Intel Quartus Prime software support that changes state of CRAM bits for testing purposes
- Hierarchy tagging in the Intel Quartus Prime software
- Triple Mode Redundancy (TMR) used for the Secure Device Manager and critical on-chip state machines

In addition to the SEU mitigation features listed above, the Intel 14-nm Tri-Gate process technology used for Intel Stratix 10 devices is based on FinFET transistors which have reduced SEU susceptibility versus conventional planar transistors.

1.26. Document Revision History for the Intel Stratix 10 GX/SX Device Overview

Document Version	Changes
2018.08.08	Made the following changes: <ul style="list-style-type: none">• Changed the specs for QDRII+ and QDRII+ Xtreme and added specs for QDRIV in the "External Memory Interface Performance" table.• Updated description of the power options in the "Sample Ordering COde and Available Options for Intel Stratix 10 Devices" figure.• Changed the description of the technology and power management features in the "Intel Stratix 10 FPGA and SoC Common Device Features" table.• Changed the description of SmartVID in the "Power Management" section.• Changed the direction arrow from the coefficient registers block in the "DSP Block: High Precision Fixed Point Mode" figure.
2017.10.30	Made the following changes: <ul style="list-style-type: none">• Removed the embedded eSRAM feature globally.• Removed the Low Power (VID) and Military operating temperature options, and package code 53 from the "Sample Ordering Code and Available Options for Stratix 10 Devices" figure.• Changed the Maximum transceiver data rate (chip-to-chip) specification for L-Tile devices in the "Key Features of Intel Stratix 10 Devices Compared to Stratix V Devices" table.
2016.10.31	Made the following changes: <ul style="list-style-type: none">• Changed the number of available transceivers to 96, globally.• Changed the single-precision floating point performance to 10 TeraFLOPS, globally.• Changed the maximum datarate to 28.3 Gbps, globally.• Changed some of the features listed in the "Stratix 10 GX/SX Device Overview" section.• Changed descriptions for the GX and SX devices in the "Stratix 10 Family Variants" section.• Changed the "Sample Ordering Code and Available Options for Stratix 10 Devices" figure.
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